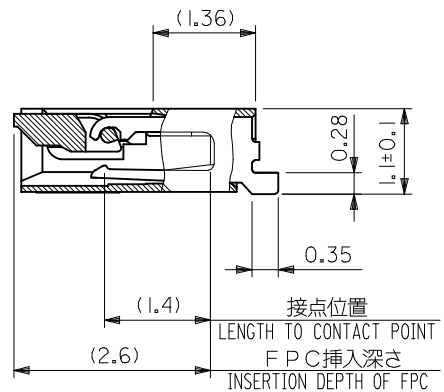
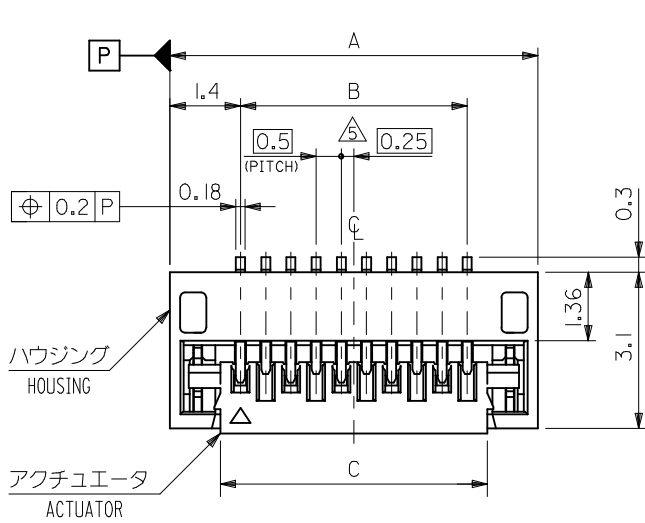
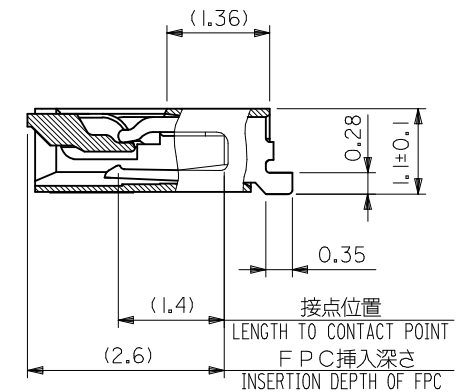


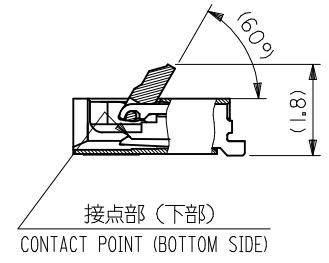
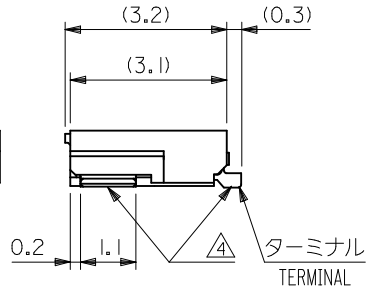
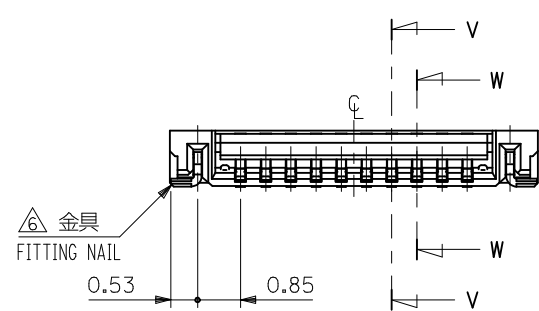
10 9 8 7 6 5 4 3 2 1



断面 V-V 奇数極 (ODD CIRCUIT)  
SECT. V-V (Scale 15:1)



断面 W-W 偶数極 (EVEN CIRCUIT)  
SECT. W-W (Scale 15:1)

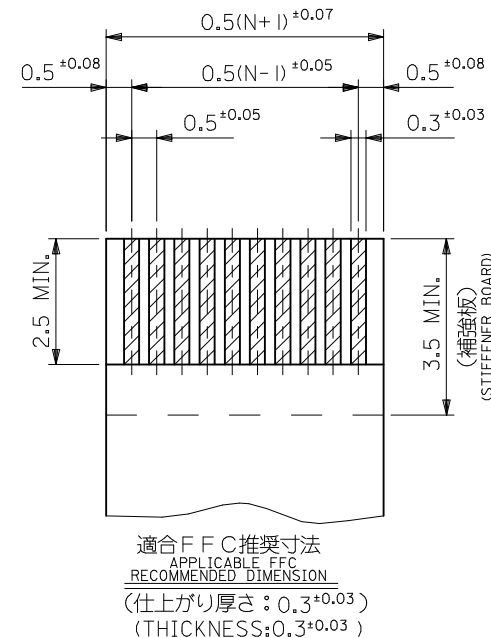
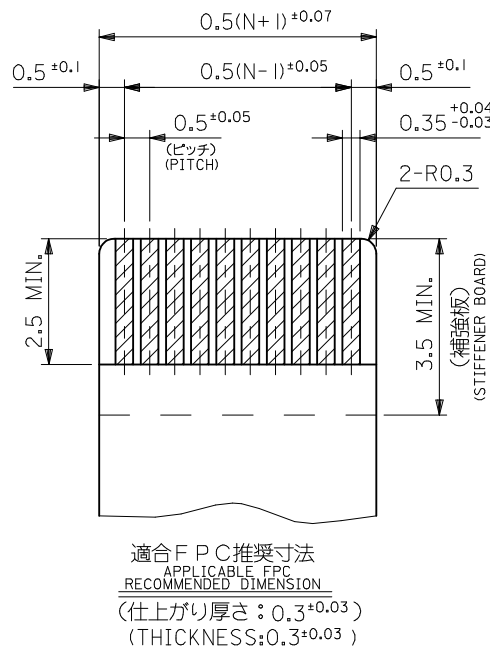
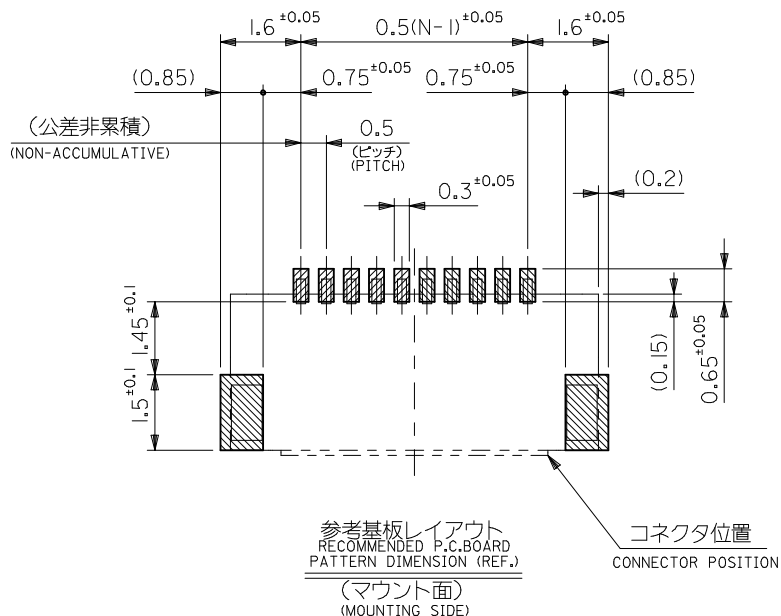


(アクチュエータが開いた状態)  
(WHEN ACTUATOR IS OPENED)

9.3	8.5	11.3	51441-1871	51441-1829	18
8.8	8.0	10.8	51441-1771	51441-1729	17
8.3	7.5	10.3	51441-1671	51441-1629	16
6.3	5.5	8.3	51441-1271	51441-1229	12
5.8	5.0	7.8	51441-1171	51441-1129	11
5.3	4.5	7.3	51441-1071	51441-1029	10
4.8	4.0	6.8	51441-0971	51441-0929	9
4.3	3.5	6.3	51441-0871	51441-0829	8
3.8	3.0	5.8	51441-0771	51441-0729	7

C	B	A	EMBOSSED TAPE	製品番号	極数
			ORDER No. オーダー番号	MATERIAL No.	CIRCUIT

REVISED EC NO: J2008-4048 DRWN: MABEI 2008/06/13 CHKD: THARUYAMA 2008/06/16 APPR: NUKITA 2008/06/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1		DESIGN UNITS METRIC		MODEL NO.	
	10 UNDER	±0.2	DRAWN BY M. NAGATA	DATE 2004/03/23	TITLE 0.5 FPC CONN. (E/O) HSG ASSY BTM CONT(H=1.1) GOLD PLATING -LEAD FREE-					
	10 OVER 30 UNDER	±0.25	CHECKED BY K. TOJO	DATE 2004/03/23	MOLEX INCORPORATED					
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE 2004/03/23	DOCUMENT NO. SD-51441-009					
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 1 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



注記 NOTES

1. 使用材料 MATERIAL

ハウジング : 液晶ポリマー ガラス充填, UL94V-0 (ベージュ)  
 HOUSING LIQUID CRYSTAL POLYMER GLASS FILLED, UL94V-0(BEIGE)  
 アクチュエータ: ポリフェニレンサルファイド ガラス充填, UL94V-0 (黒)  
 ACTUATOR POLYPHENYLENE SULFIDE GLASS FILLED, UL94V-0(BLACK)  
 ターミナル : リン青銅 (t=0.18)  
 TERMINAL PHOSPOR BRONZE  
 金具 : リン青銅 (t=0.15)  
 FITTING NAIL PHOSPOR BRONZE

3. エンボステープ梱包時は、アクチュエータが閉じた状態とする。

IN THE PACKAGE, ACTUATOR OF PART NO.51441-\*\*-11 SHOULD BE CLOSED.

△ソルダータール及び金具の平坦度は、0.1以下。  
 SOLDER TAIL AND FITTING NAIL COPLANARITY TO BE 0.1 MAXIMUM.

△偶数極に適用。  
 APPLY FOR EVEN CIRCUIT.

△パターンはくり止め用金具  
 FITTING NAIL FOR PREVENTION OF PEELING OF PCB PATTERN.

7. 本製品は51441-\*\*-21の鉛フリー品である。  
 THIS PRODUCT IS LEAD FREE OF 51441-\*\*-21

FPC/FFCについて:

打抜き方向は導体側から補強板側を推奨いたします。  
 導体部については軟銅箔35マイクロメートルまたは50マイクロメートルを推奨いたします。  
 ABOUT FPC/FFC  
 RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.  
 RECOMMENDED CONDUCTOR SPEC :  
 THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER

FPCについて:

補強フィルム材質はポリイミドを推奨します。  
 接着剤は熱硬化接着剤を推奨します。  
 ABOUT FPC  
 RECOMMENDED MATERIAL :  
 STIFFENER FILM : POLYIMIDE  
 BONDING AGENT : THERMOSETTING BONDING AGENT

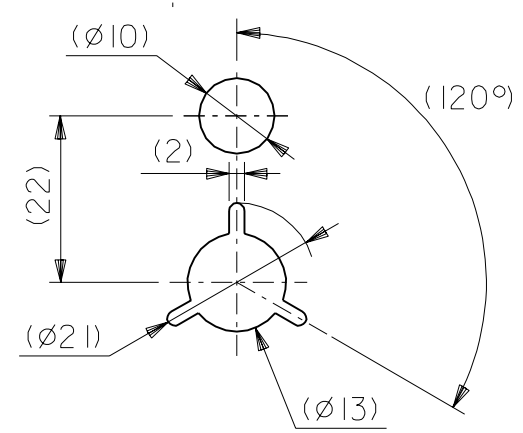
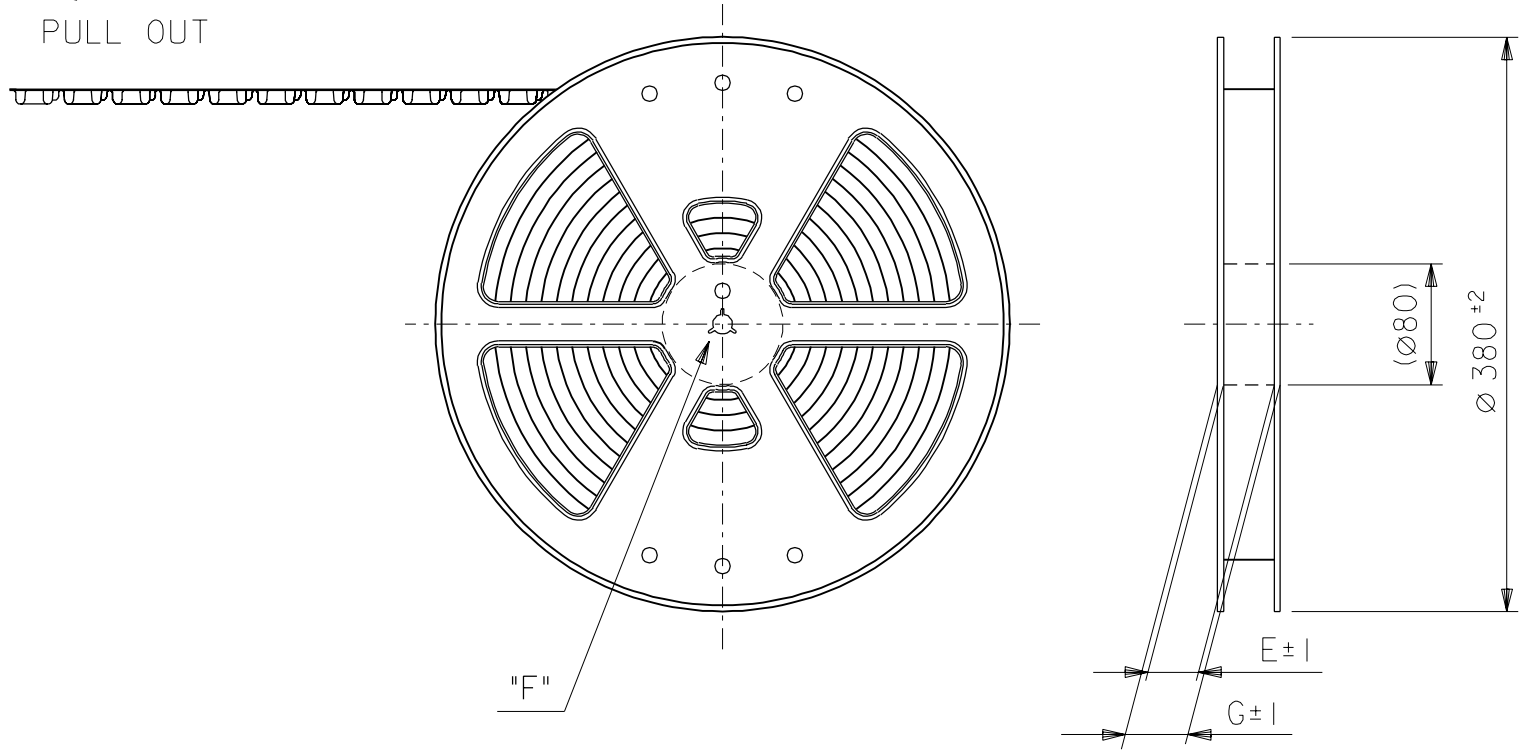
2. メッキ仕様 PLATING

ターミナル TERMINAL  
 ニッケル下地金メッキ  
 GOLD OVER NICKEL PLATING  
 金具 FITTING NAIL  
 ニッケル下地金メッキ  
 TIN OVER NICKEL PLATING

REVISED EC NO: J2008-4048 DRWN: MWABEI 2008/06/13 CHKD: THARUYAMA 2008/06/16 APPR: NUKITA 2008/06/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		51441-**-29		MODEL NO.		
	10 UNDER ±0.2		DRAWN BY DATE M. NAGATA 2004/03/23		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
	10 OVER 30 UNDER ±0.25		CHECKED BY DATE K. TOJO 2004/03/23		TITLE 0.5 FPC CONN. (E/O) HSG ASSY BTM CONT(H=1.1) GOLD PLATING -LEAD FREE-				
	30 OVER ±0.3		APPROVED BY DATE M. SASAO 2004/03/23						
ANGULAR ±3 °		MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-51441-009		MOLEX INCORPORATED			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					SHEET NO. 2 OF 2

DWG. NO.  
SD-51441-010

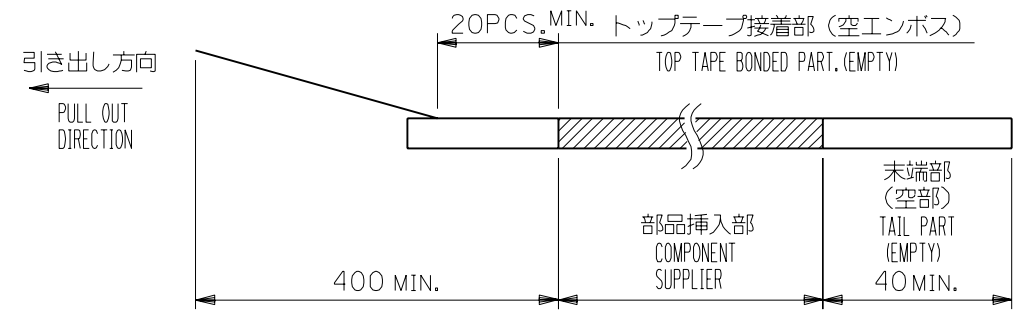
引き出し方向  
PULL OUT



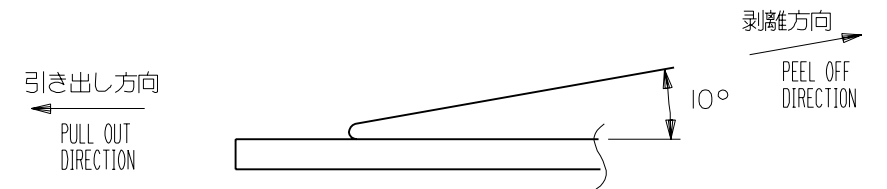
DETAIL "F"

注記 NOTES

- 製品詳細寸法については、図面SD-51441-003を参照下さい。  
RE DETAILED DIMENSION, SEE SD-51441-003.
- 梱包数量：3000個/リール  
NUMBER OF CONNECTORS : 3000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：0.1~1.3N(10~130gf) (剥離方向は下図参照)  
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)  
PEELING OFF FORCE OF TOP TAPE : 0.1~1.3N(10~130gf)  
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG,)  
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.  
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.



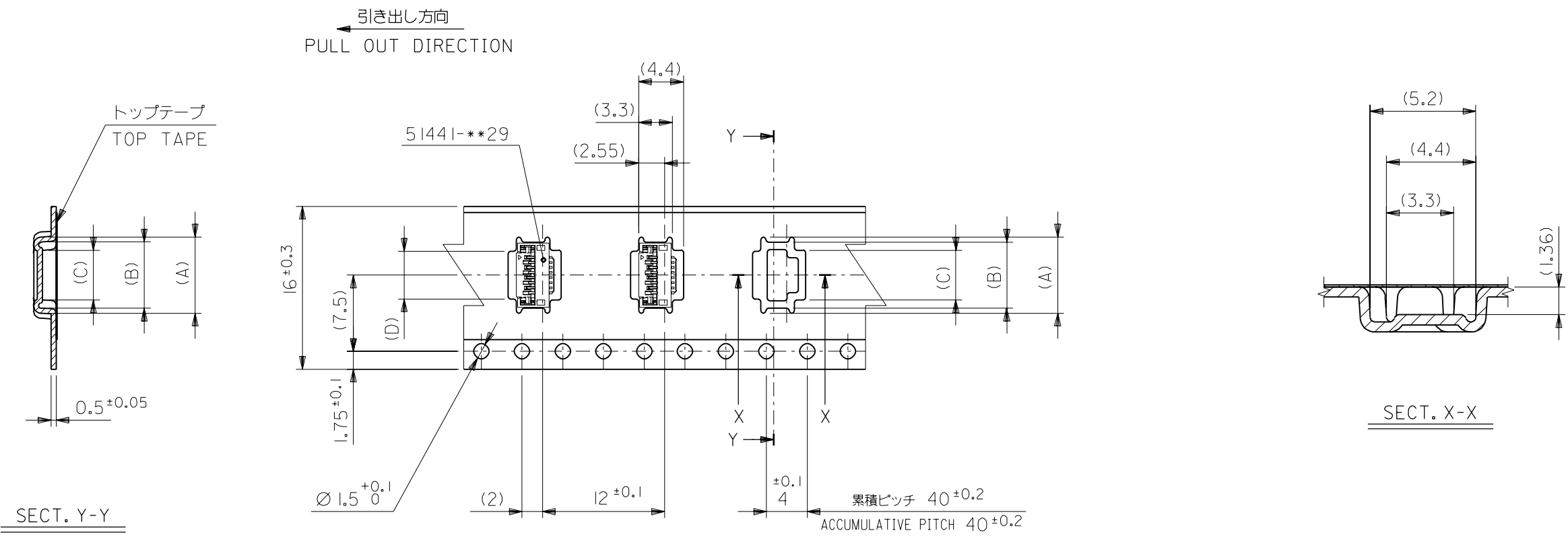
- 材料 (MATERIAL)  
キャリアテープ (CARRIER TAPE) : ポリプロピレン (POLYPROPYLENE)  
トップテープ (TOP TAPE) : PET, PE, PEF  
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>  
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAINED>
- 本製品は51441-\*\*-91の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 51441-\*\*-91

DO NOT SCALE DRAWING

EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		RELEASED '04/03/23	MATERIAL 材料 注記参照 SEE NOTES	GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		51441-**-91		MODEL No.	DIMENSIONS:		SHT	REV
EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		EC NO. J2004-3278 DRWN: M.NAGATA CH'K: K.TOJO APPR: M.SASAO		FINISH 仕上げ	10 UNDER 未満 ±0.2	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	mm INCH mm ONLY			
EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		0		WIRE RANGE 適用電線範囲	10 OVER 以上 30 UNDER 未満 ±0.25	DRAWN BY & DATE M.NAGATA '04/03/23	TITLE: Embstp Pkg FOR 0.5 FPC Conn (E/O) Btm Cont GOLD PLATING (Hgt=1.1mm) -LEAD FREE-					
EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:				INS. RANGE 被覆外径	30 OVER 以上 ±0.3	APPROVED BY & DATE M.SASAO '04/03/23	MOLEX INCORPORATED					
									ANGLE 角度	±3°	CAD FILENAME SD-51441-010.S01	MATERIAL NO. SEE CHART	DRAWING NO. SD-51441-010	SHEET NO. 1 OF 3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		SIZE B

SD-51441-010.S01

DWG. NO.  
SD-51441-010



16mm幅キャリアテープ  
16mm WIDTH CARRIER TAPE

16	21.4	17.4	4.7	4.89	6.5	7.5	51441-0871	8
			4.2	4.39	6.0	7.0	51441-0771	7
キャリアテープ幅 CARRIER TAPE WIDTH	G	E	(D)	(C)	(B)	(A)	MATERIAL NO.	種数 CKT.

51441-***71		MODEL No.	DIMENSIONS:		SHT	REV
SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	<input type="checkbox"/> mm	<input type="checkbox"/> INCH	<input checked="" type="checkbox"/> mm	REVISE ON CAD ONLY
DRAWN BY & DATE M.NAGATA '04/03/23		TITLE: Embstp Pkg FOR 0.5 FPC Conn (E/O) Btm Cont GOLD PLATING (Hgt=1.1mm) -LEAD FREE-				
CHECKED BY & DATE K.TOJO '04/03/23		MOLEX INCORPORATED				
APPROVED BY & DATE M.SASAO '04/03/23		MATERIAL NO.	DRAWING NO.	SHEET NO.		
CAD FILENAME SD-51441-010.S02		SEE CHART	SD-51441-010	2 OF 3		

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	RELEASED '04/03/23	DESCRIPTION
				EC NO. J2004-3278 DRWN: M.NAGATA CHK: K.TOJO APPR: M.SASAO	MATERIAL 材料 注記参照 SEE NOTES
				0	FINISH 仕上げ //
					WIRE RANGE 適用電線範囲 //
					INS. RANGE 被覆外径 //

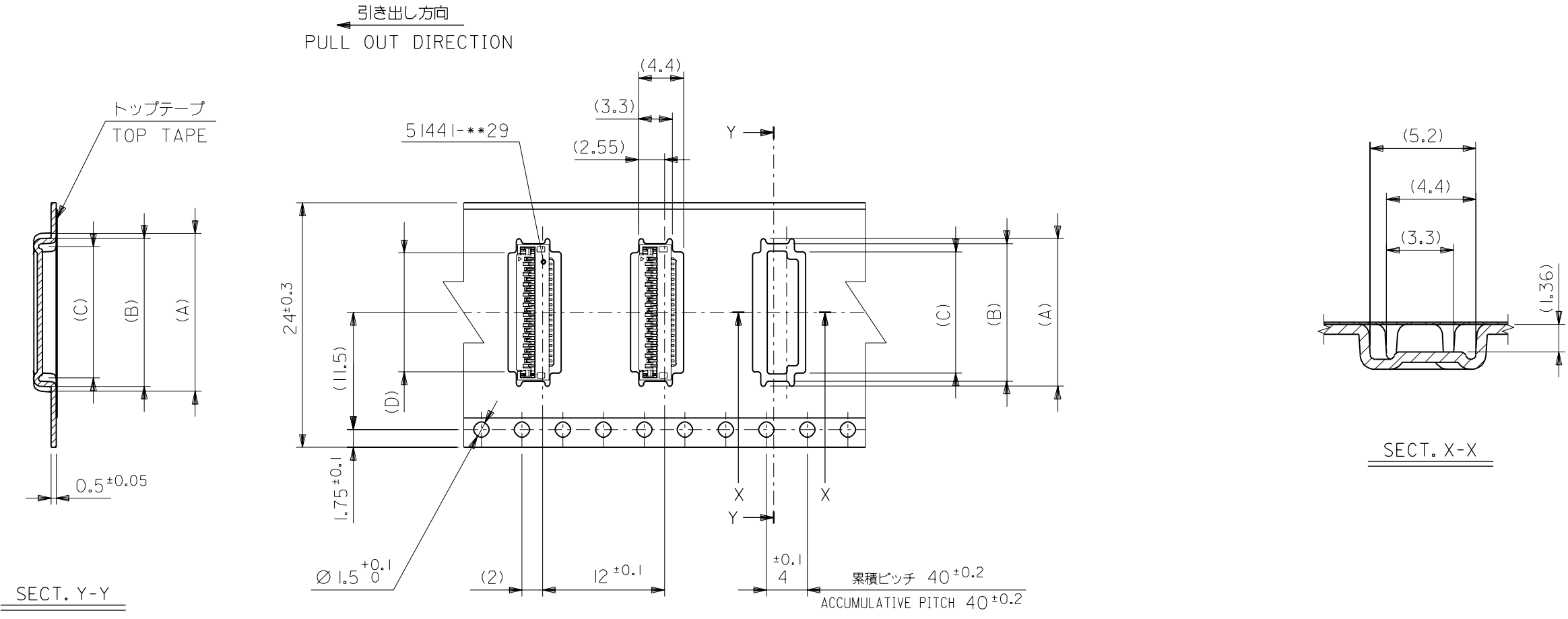
GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	
10 UNDER 未満	±0.2
10 OVER 以上 30 UNDER 未満	±0.25
30 OVER 以上	±0.3
ANGLE 角度	±3°

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.

DO NOT SCALE DRAWING

SD-51441-010.S02

DWG. NO.  
SD-51441-010



24mm幅キャリアテープ  
24mm WIDTH CARRIER TAPE

24	29.4	25.4	9.7	9.89	11.5	12.5	51441-1871	18
			9.2	9.39	11.0	12.0	51441-1771	17
			8.7	8.89	10.5	11.5	51441-1671	16
			6.7	6.89	8.5	9.5	51441-1271	12
			6.2	6.39	8.0	9.0	51441-1171	11
			5.7	5.89	7.5	8.5	51441-1071	10
5.2	5.39	7.0	8.0	51441-0971	9			
キャリアテープ幅 CARRIER TAPE WIDTH	G	E	(D)	(C)	(B)	(A)	MATERIAL NO.	種数 CKT.

DO NOT SCALE DRAWING

EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	EC NO. DRWN: CHK: APPR:	RELEASED '04/03/23 EC NO. J2004-3278 DRWN: M.NAGATA CHK: K.TOJO APPR: M.SASAO	DESCRIPTION MATERIAL 材料 注記参照 SEE NOTES FINISH 仕上げ // WIRE RANGE 適用電線範囲 // INS. RANGE 被覆外径 //
0						

GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差	SCALE —#—	DESIGN UNITS <input checked="" type="checkbox"/> mm <input type="checkbox"/> INCH	THIRD ANGLE PROJECTION <input checked="" type="checkbox"/> THIRD ANGLE	DIMENSIONS: <input type="checkbox"/> mm <input type="checkbox"/> INCH <input checked="" type="checkbox"/> mm ONLY	SHT REV
10 UNDER 未満 ±0.2	DRAWN BY & DATE M.NAGATA '04/03/23	TITLE: Embstp Pkg FOR 0.5 FPC Conn (E/O) Btm Cont GOLD PLATING (Hgt=1.1mm) -LEAD FREE-			REVISE ON CAD ONLY
10 OVER 以上 30 UNDER 未満 ±0.25	CHECKED BY & DATE K.TOJO '04/03/23	MOLEX INCORPORATED			
30 OVER 以上 ±0.3	APPROVED BY & DATE M.SASAO '04/03/23	CAD FILENAME SD-51441-010.S03	MATERIAL NO. SEE CHART	DRAWING NO. SD-51441-010	SHEET NO. 3 OF 3
ANGLE 角度 ±3°	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.				SIZE B

SD-51441-010.S03